ELEVATING PREMIUM INTO NEW DIMENSIONS MediaTek Dimensity 8100 | MediaTek Dimensity 8000

4.

Incredible TSMC 5nm-class Smartphone Chip

The MediaTek Dimensity 8100 & 8000 are built using TSMC N5 (5nm-class) production, giving users exceptional power-efficiency and longer battery life.

Best-in-class HFR Gaming Experience

Extreme performance with incredible power-efficiency for intense high frame-rate gaming sessions that just keep going.

- Super-Cores 4x Arm Cortex-A78
- Efficiency Cores 4x Arm Cortex-A55
- Over 25% better CPU power-efficiency vs previous generation Dimensity
- UFS 3.1 storage and quad-channel LPDDR5

MediaTek MiraVision 780

25% speed upgrade over previous generation Dimensity, plus the latest HDR and streaming technologies for multimedia playback.

- MediaTek Intelligent Display Sync 2.0
- CUVA HDR-vivid certified Android smartphone platform
- HDR10+ Adaptive support
- 4K AV1 media decoding



- Arm Mali G610 MC6 GPU
- MediaTek HyperEngine 5.0 gaming technologies

MediaTek
Dimensity 8100M
Di
DiArm Cortex-A78 up to 2.85GHzA
Up to 20% GPU Frequencyu
U
Boost in Games

MediaTek Dimensity 8000 Arm Cortex-A78 up to 2.75GHz



MediaTek Imagiq 780

An immensely powerful 14-bit HDR-ISP gives the fastest, clearest HDR photos & video capture, enabling two cameras recording at the same time with three exposures per frame.

- Most powerful 5Gpixel/s ISP in its class
- Simultaneous dual camera HDR video recording
- 200MP camera support
- AI-NR/HDR photos
- 4K60 HDR10+ video capture
- AI-Motion unblur
- 2X lossless zoom





MediaTek APU 580

Featuring a design that maximizes efficiency at every pipeline step, our 5th generation AI processor offers class-leading power-effective performance in a wide variety of AI-tasks.

- Ideal for AI-multimedia, AI-camera, and social video experiences
- End-to-end upgrade maximizes efficiency at every pipeline step
 - MediaTek Dimensity 8100 2.75X speed boost over previous generation Dimensity

MediaTek Dimensity 8000

2.5X speed boost over previous generation Dimensity

3GPP Release-16 5G Smartphone Modem

Unmatched 5G technologies that connect further, faster and with better power efficiency, so you can leave 5G on all day, every day.

- Latest Release-16 standard 5G modem
- MediaTek 5G UltraSave 2.0 power-saving enhancement suite including R16 WUS and SCell Dormancy

- Latest Wi-Fi 6E 2x2 with MediaTek Wi-Fi Fast Path technology
- New Bluetooth 5.3
- New Wi-Fi/Bluetooth hybrid coexistence design
- Bluetooth LE Audio technology with Dual-Link True Wireless Stereo Audio
- New Beidou III-B1C GNSS support

MediaTek Dimensity 8100 | 8000 SPECIFICATIONS

Process	TSMC N5 (5nm-class)	
CPU	4x Arm Cortex-A78	
	Dimensity 8100 up to 2.85GHz Dimensity 8000 up to 2.75GHz	5G
	4x Arm Cortex-A55	
GPU	Arm Mali-G610 GPU MC6	MediaTek Dimensity 8100
	MediaTek HyperEngine 5.0	Dimensity 8100
	Dimensity 8100 up to 20% frequency boost	
AI	MediaTek APU 580	
	Dimensity 8100 up to 25% frequency boost	
Camera	MediaTek Imagiq 780 14-bit HDR-ISP fusion up to 5Gpixel/s	
	Up to 200MP Primary Camera Twin camera, Tri-exposure HDR videography	5G
Display	MediaTek MiraVision 780	MediaTek
	168Hz Full HD+	Dimensity 8000
	Dimensity 8100 also offers 120Hz WQHD+	
	MediaTek Intelligent Display Sync 2.0	
Audio	Bluetooth LE Audio technology with Dual-Link True Wireless Stereo Audio	
Connectivity	Wi-Fi 6E 2x2 and Bluetooth 5.3 Wi-Fi/Bluetooth hybrid coexistence design	
Memory	Quad-channel LPDDR5	
Storage	UFS 3.1	
Modem	3GPP Release 16 5G modem MediaTek UltraSave 2.0 2CC Carrier Aggregation (200MHz) 5G NR	
Customization	Dimensity 5G Open Resource Architecture ready	

- 2CC Carrier Aggregation (200MHz) 5G NR
- 5G+5G Dual SIM Dual Standby

